



2858

PATENT  
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : D.Y.Shih, et al.  
Serial Number : 09/254,769  
Filing Date : March 11, 1999  
Examiner : V. Nguyen  
Group Art Unit : 2858  
For : WAFER SCALE HIGH DENSITY  
PROBE ASSEMBLY,  
APPARATUS FOR USE THEREOF  
AND METHODS OF  
FABRICATION THEREOF

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Sir:

In response to the Official Action dated May 27, 2003, please amend the above-identified application as follows:

Amend the Claims as set forth hereinafter.

Insert the enclosed Abstract of the Disclosure into this case.

RECEIVED  
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TECHNOLOGY CENTER 2800